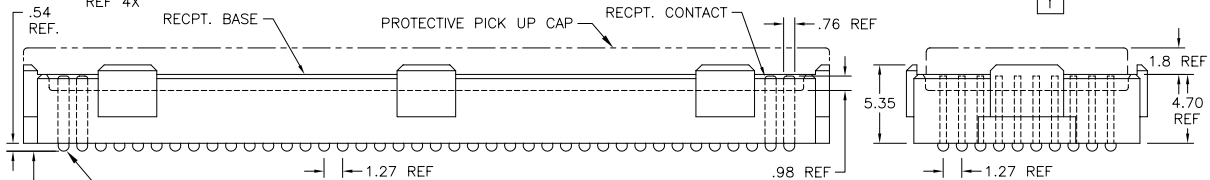
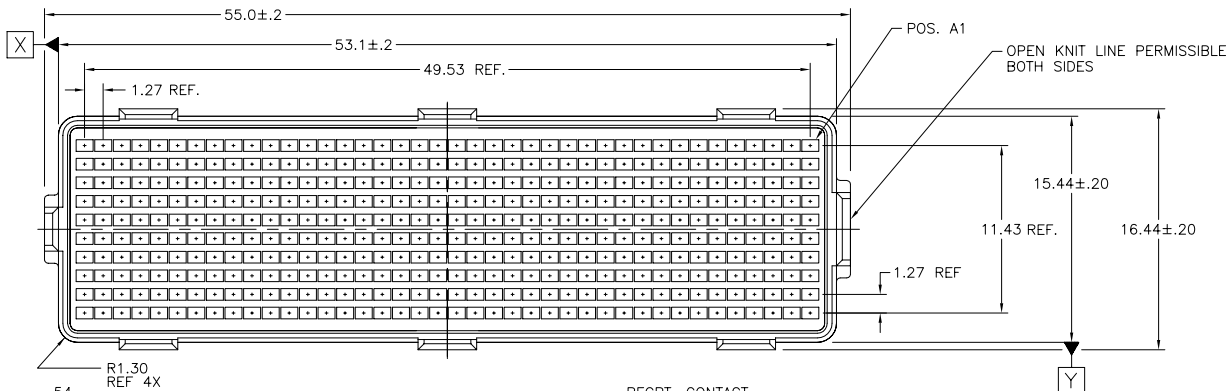


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PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
74388-001	YES	15u" (.38u") Au OVER Ni	SnPb
74388-001LF			SnAgCu LEAD FREE (5)(6)
74388-101	YES	30u" (.76u") Au OVER Ni	SnPb
74388-101LF			SnAgCu LEAD FREE (5)(6)
74388-201	YES	SEE NOTE 4.	SnPb
74388-201LF			SnAgCu LEAD FREE (5)(6)



Ø.760 SOLDER BALLS  
NOTE 2.

⊕ Ø.30 X Y

.203

mat'l code	SEE NOTE 1	surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family
tr	ec'n no	dr	date	tolerances unless otherwise specified			MEG-ARRAY
K	v06-0560	LP	2006/06/23	angles	Xx3	MM	title
-	-	-	-		XXXB		6mm RECEPT. ASSY
E	v90472	DRW	07/02/99	0° ±2'	XXXX051	scale 3:1	10 X 40= 400 POS.
F	v00181	HLJ	06/30/00	dr	D WAUGHEN	1.5.98	dwg no
G	v20006	DRW	01/07/02	engr	T LEMKE	1.5.98	sheet 1 of 3
H	v03-0679	DAI	06/19/03	chr	T LEMKE	1.5.98	size
J	v04-0940	VS	10/18/04	appd	T LEMKE	1.5.98	A4
sheet index	revision sheet	K	K	K			74388
		1	2	3			type
							CUSTOMER Drawing



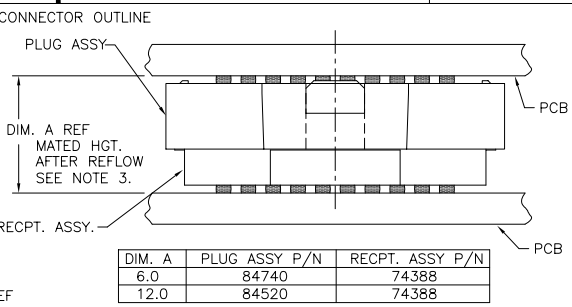
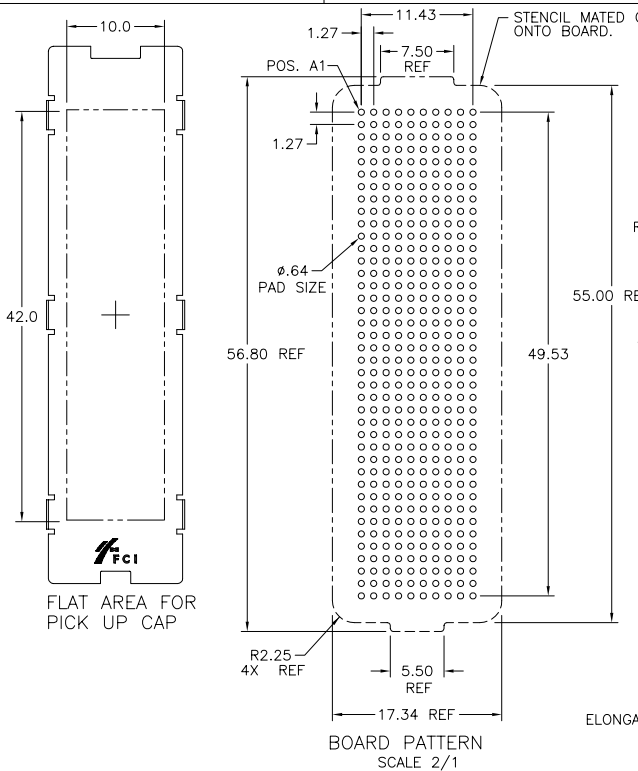
form A4mmXlc

PDM: Rev:K STATUS Released Printed: Oct 21, 2010

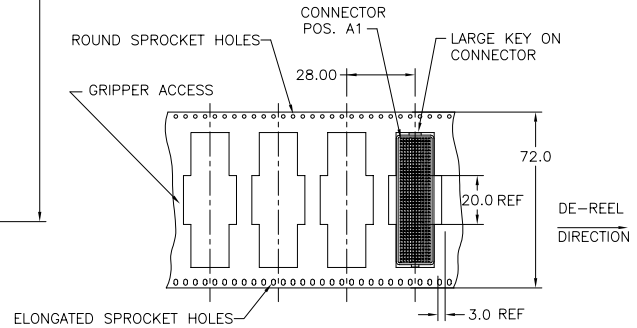


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MATED HEIGHT AFTER REFLOW IS BASED ON  $\phi$  .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.



mat'l code	SEE NOTE 1	surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family
ltr	ec'n no	dir	date	tolerances unless otherwise specified		MM	MEG-ARRAY
K				angles	Xx3		title
				or ±2°	XXX-B	scale 2:1	6mm RECEPT. ASSY. 10x40= 400 POS.
				dr	D WAUGHEN 1.5.98		dwg no
				engr	T LEMKE 1.5.98		74388
				chr	T LEMKE 1.5.98		sheet 2 of 3
				appd	T LEMKE 1.5.98		size A4
sheet index	revision sheet						type
							CUSTOMER Drawing

NOTES:

①. MAT'L:

HOUSING: LCP  
CONTACT: COPPER ALLOY

PLATING

CONTACT: (SEE TABLE ON SHEET1)  
SOLDER BALL: (SEE TABLE ON SHEET1)  
EUTECTIC SnPb OR LEAD FREE  
95.5Sn/4Ag/0.5Cu

- ②. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- ④. PLATING FOR -2XX SERIES DASH NOS: Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- ⑤. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- ⑥. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

mat'l code SEE NOTE 1				surface ASME Y14.5 <input checked="" type="checkbox"/> ASME Y14.5		tolerance ASME Y14.5		projection 		product family MEG-ARRAY	
ltr	ecrn no	dr	date	tolerances unless otherwise specified		angles X+3 XXX-B XXX+051		MM scale 2:1		title 6mm RECP. ASSY. 10x40= 400 POS.	
K				dr D WAUGHEN 1.5.98		enqr T LEMKE 1.5.98		chr T LEMKE 1.5.98		appd T LEMKE 1.5.98	
sheet index		revision sheet		FCI		dwg no 74388		sheet 3 of 3		size A4	
						type CUSTOMER Drawing					